CND0333A

Infrared Optical Module (IrDA)

Infrared data link for cellular phones, peripheral devices

■ Features

- Compliant with IrDA Ver.1.4
- Light emitting function for remote controller
- Corresponding low I/O (interface) voltage: 1.5 V
- Corresponding reflow solder (260°C)
- Ultra-small top view package (1.5 mm \times 8.2 mm \times 1.7 mm)

■ Type

• GaAlAs LED + IC + PIN Photodiode

■ Absolute Maximum Ratings $T_a = 25$ °C±3°C

Parameter	Symbol	Rating	Unit	
Operating supply voltage	V _{CC}	-0.5 to $+3.8$	V	
LED operating supply voltage	V_{LEDA}	-0.5 to $+7.0$	V	
Input/output supply voltage	V _{IO}	-0.5 to +3.8	V	
TX Input voltage	V _{TX}	-0.5 to +3.8	V	
Shutdown input voltage	V_{SD}	-0.5 to +3.8	V	
LED operating supply current *	I_{LEDA}	300	mA	
Operating ambient temperature	T _{opr}	-20 to +70	°C	
Storage temperature	T _{stg}	-30 to +85	°C	

Note) *: $tw \le 90 \mu s$, $Duty \le 25 \%$

■ Operationg Condition

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Operating supply voltage	V _{CC}		2.5	2.85	3.3	V
LED operating supply voltage	V _{LEDA}		3.0		4.5	V
Input/output supply voltage	V _{IO}		1.5	1.85	V _{CC}	V

$\blacksquare \ \, \text{Electrical-Optical Characteristics} \quad V_{LEDA} = 3.0 \ V \ \text{to} \ 4.5 \ V, V_{CC} = 2.85 \ V, V_{IO} = 1.85 \ V, T_a = 25 ^{\circ}\text{C} \pm 3 ^{\circ}\text{C}$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Shut down supply current *Fig. 1	I _{CCSD}	$V_{TXD} = 0.5 \text{ V},$ $V_{IO} \ge V_{SD} \ge V_{IO} - 0.5 \text{ V (SD = High)}$	_	0.01	0.2	μΑ
High level supply current (Idle) *Fig. 1	I _{CCH}	(FIR mode / RC mode) $E_I = 0 \text{ mW/cm}^2$, $V_{TXD} = 0.5 \text{ V}$, $V_{SD} \le 0.5 \text{ V}$		580	800	μΑ
		(SIR mode) $E_I = 0 \text{ mW/cm}^2, V_{TXD} = 0.5 \text{ V}, V_{SD} \le 0.5 \text{ V}$	_	300	400	
Low level supply current (Active) *Fig. 1	ī	(FIR mode / RC mode) $E_I = 9.0 \text{ mW/cm}^2$, $V_{TXD} = 0.5 \text{ V}$, $V_{SD} \le 0.5 \text{ V}$	_	980	1270	μΑ
	I_{CCL}	(SIR mode) $E_I = 9.0 \text{ mW/cm}^2, V_{TXD} = 0.5 \text{ V}, V_{SD} \le 0.5 \text{ V}$	_	350	460	μιι
TX High level supply current (Active) *Fig. 1	I _{CCTXH}	$(FIR \bmod / RC \bmod) \\ V_{IO} \ge V_{TXD} \ge V_{IO} - 0.5 \ V \ (TXD = High) \\ E_I = 0 \ mW/cm^2, V_{SD} \le 0.5 \ V$		1200	1560	μΑ
		$(SIR mode) \\ V_{IO} \ge V_{TXD} \ge V_{IO} - 0.5 \text{ V (TXD} = \text{High)} \\ E_I = 0 \text{ mW/cm}^2, V_{SD} \le 0.5 \text{ V}$	_	600	780	
High level input/output supply current (Idle) *Fig. 1	I _{IOH}	(FIR mode / RC mode) $E_I = 0 \text{ mW/cm}^2$, $V_{TXD} = 0.5 \text{ V}$, $V_{SD} \le 0.5 \text{ V}$	0	0	5	μА
		(SIR mode) $E_I = 0 \text{ mW/cm}^2, V_{TXD} = 0.5 \text{ V}, V_{SD} \le 0.5 \text{ V}$	0	0	5	
Low level input/output	I _{IOL}	(FIR mode / RC mode) $E_I = 9.0 \text{ mW/cm}^2, V_{TXD} = 0.5 \text{ V}, V_{SD} \le 0.5 \text{ V}$	_	360	470	μА
supply current (Active) *Fig. 1		(SIR mode) $E_I = 9.0 \text{ mW/cm}^2, V_{TXD} = 0.5 \text{ V}, V_{SD} \le 0.5 \text{ V}$	_	100	130	
TX High level input/output supply current (Active) *Fig. 1	I _{IOTXH}			80	120	μΑ
		(SIR mode) $V_{IO} \ge V_{TXD} \ge V_{IO} - 0.5 \text{ V (TXD} = \text{High)}$ $E_I = 0 \text{ mW/cm}^2, V_{SD} \le 0.5 \text{ V}$	_	40	60	
SD High level input voltage	V _{IHSD}		V _{IO} - 0.5	_	V _{IO} +0.3	V
SD Low level input voltage	V _{ILSD}		0 -0.3	_	0.5	V
Maximum reception distance *Fig. 1, 4	L _{max}	$\begin{split} &V_{SD} \leq 0.5 \text{ V} \\ &\theta_T = 0^{\circ} \pm 15^{\circ} \\ &\text{LEDie} = 3.6 \text{ mW/sr (SIR mode)} \\ &\text{LEDie} = 9 \text{ mW/sr (FIR mode)} \end{split}$	21.8	_	_	cm
RC maximum reception distance *Fig. 1	L _{maxR}	V_{LEDA} = 3.0 V, V_{SD} ≤ 0.5 V θ_T = 0° ± 15°, RC Receiver sensitivity *2 = 0.05 μW/cm ²	5.0			m
Data Rates *1			0.0096		4.0	Mbps

Note) *1: Fully Compliant to IrDA1.4 Low Power Specification from 9.6 kbps to 115.2 kbps, 4 Mbps.

RC receiver sensitivity is adjusted so that RC transfer distance is 4 m at transmitter LED radiant intensity= 8 mW/sr, peak wave length = 940 nm and duty = 50 %, where irradiance is 0.05 μ W/cm².

^{*2:} Definition of RC receiver sensitivity

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$\blacksquare \text{ Electrical-Optical Characteristics (continued)} \quad V_{LEDA} = 3.0 \text{ V to } 4.5 \text{ V}, V_{CC} = 2.85 \text{ V}, V_{IO} = 1.85 \text{ V}, T_a = 25^{\circ}\text{C} \pm 3^{\circ}\text{C}$

Parame	eter	Symbol	Conditions	Min	Тур	Max	Unit
Transmitter							
Peak emission wavelength *Fig. 1		$\lambda_{ m P}$	$(FIR mode / RC mode) \\ V_{LEDA} = 3.2 \text{ V}, V_{SD} \le 0.5 \text{ V}, Duty 1/4$	880	890	900	nm
			(SIR mode) $V_{LEDA} = 3.2 \text{ V}, V_{SD} \le 0.5 \text{ V}, \text{Duty}3/16$	875	885	900	
LED operating supply current *Fig. 1			(FIR Mode/RC Mode) $V_{LEDA} = 4.3 \text{ V, VSD} \le 0.5 \text{ V, Duty1/4}$	165	207	248	
		T	(FIR Mode/RC Mode) $V_{LEDA} = 3.0 \text{ V}, \text{ VSD} \le 0.5 \text{ V}, \text{ Duty} 1/4$	160	200	240	
LED operating supply c	current o	I_{LEDA}	(SIR Mode) $V_{LEDA} = 4.3 \text{ V}, V_{SD} \le 0.5 \text{ V}, \text{Duty}3/16$	70	91	109	mA
			(SIR Mode) $V_{LEDA} = 3.0 \text{ V}, V_{SD} \le 0.5 \text{ V}, \text{Duty}3/16$	69	90	108	
	$\theta_{\rm T} = 0 * {\rm Fig.} 1, 2$	ī	(FIR Mode/RC Mode) $V_{LEDA} = 3.0 \text{ V}, VSD \le 0.5 \text{ V}, Duty1/4$	27	55	83	mW/sr
Center radiant intensity *3		I _e	(SIR Mode) $V_{LEDA} = 3.0 \text{ V}, V_{SD} \le 0.5 \text{ V}, \text{Duty}3/16$	13	27	40	
	$\theta_{\rm T} = \pm 15 {}^{*{\rm Fig.} 1, 2, 10}$	I _{e15}	(FIR Mode/RC Mode) $V_{LEDA} = 3.0 \text{ V}, V_{SD} \le 0.5 \text{ V}, \text{Duty } 1/4$	23	38	57	- mW/sr
			(SIR Mode) $V_{LEDA} = 3.0 \text{ V}, V_{SD} \le 0.5 \text{ V}, \text{Duty}3/16$	7	19	28	
TX high level input vol	tage	V _{IH(TX)}		V _{IO} - 0.5	_	V _{CC} +0.3	V
TX low level input volta	age	V _{IL(TX)}		0 -0.3	_	0.5	V
TX pulse width (SIR) *I	Fig. 1, 8	$t_{WT(SIR)}$	Bit Rate = 115.2 kbps, $V_T = 1/2 \times V_{IO}$	_	1.6		μs
TX pulse width (FIR) *I	Fig. 1, 8	t _{WT(FIR)}	Bit Rate = 4.0 Mbps, $V_T = 1/2 \times V_{IO}$	_	125		ns
Optical pulse width (FII	R1) *Fig. 1, 3	t _{WO(FIR1)}	$\begin{aligned} &V_{SD} \leq 0.5 \text{ V, TXD } t_r / t_f \leq 20 \text{ ns,} \\ &t_W = 125 \text{ ns} \pm 1 \text{ ns, (Single pulse)} \end{aligned}$	115	125	135	ns
Optical pulse width (FIR2) *Fig. 1, 3		t _{WO(FIR2)}	$\begin{aligned} V_{SD} &\leq 0.5 \text{ V, TXD } t_r / t_f \leq 20 \text{ ns,} \\ t_W &= 250 \text{ ns} \pm 1 \text{ ns, (Double pulse)} \end{aligned}$	240	250	260	ns
TX half-angle		θ_{T}		±15	_		0
Rise time *Fig. 1, 3		t _r	$R_L = 50 \Omega$	_	_	40	ns
Fall time *Fig. 1, 3		t_{f}	$R_L = 50 \Omega$		_	40	ns
TX wake up time *Fig. 5		t_{TWU}		200	_	1 000	μs
Intensity delay time *Fig	. 1, 3	I_{DT}		_	_	200	ns
Maximum pulse width		t _{WLEDmax}	$TXD = Low \rightarrow High$	20	50	100	μs
Overshoot		O_S			_	25	%

Note) *3: Eye-Safety IEC60825-1 Class1 Eye safe

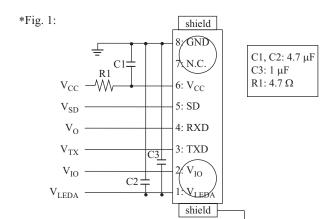
 $\blacksquare \ \, \text{Electrical-Optical Characteristics (continued)} \quad V_{LEDA} = 3.0 \ V \ \text{to} \ 4.5 \ V, \\ V_{CC} = 2.85 \ V, \\ V_{IO} = 1.85 \ V, \\ T_a = 25 ^{\circ} \text{C} \pm 3 ^{\circ} \text{C}$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Receiver						
Minimum input irradiance *Fig. 1	E _{I min1}	(SIR mode) Bit Rate = 115.2 kbps, $V_{SD} \le 0.5 \text{ V}$, $\theta_T = 0^{\circ} \pm 15^{\circ}$	_		7.6	
	E _{I min2}	(FIR Mode) Bit Rate = 4.0 Mbps, $V_{SD} \le 0.5 \text{ V}$, $\theta_T = 0^{\circ} \pm 15^{\circ}$	_		19.0	- μW/cm ²
Maximum input irradiance *Fig. 1	E _{I mix}	$V_{SD} \le 0.5 \text{ V}, \theta_T = 0^{\circ} \pm 15^{\circ}$	500	_	_	mW/cm ²
RX high level output voltage *Fig. 1	V _{OH(RX)}	Non signal condition E_I = 0 I_{OH} = -200 μA , V_{SD} ≤ 0.5 V	V _{IO} -0.3		V_{IO}	V
RX low level output voltage *Fig. 1	V _{OL(RX)}	$I_{OL} = 1.8 \text{ mA}, V_{SD} \le 0.5 \text{ V}$	0	_	0.5	V
RX half angle	θ_{R}		±15	_	_	0
Output pulse width (SIR) *Fig. 1,9	$t_{WR(SIR)}$	$V_{SD} \le 0.5 \text{ V}, C_L = 15 \text{ pF},$ 9.6 kbps to 115.2 kbps	1.0	_	4.0	μѕ
Output pulse width (FIR1) *Fig. 1, 9	t _{WR(FIR1)}	$V_{SD} \le 0.5 \text{ V}, C_L = 15 \text{ pF},$ $4 \text{ Mbps}, t_W = 125 \text{ ns}$ (Single pulse)	85		165	ns
Output pulse width (FIR2) *Fig. 1, 9	t _{WR(FIR2)}	$V_{SD} \le 0.5 \text{ V}, C_L = 15 \text{ pF},$ $4 \text{ Mbps}, t_W = 250 \text{ ns}$ (Double pulse)	195		290	ns
RX wake up time *Fig. 1, 6	t _{Rwu}	$V_{SD} \le 0.5 \text{ V}, E_I = 19.0 \ \mu\text{W/cm}^2$	_	100	200	μs
Receiver latency time *Fig. 1, 7	$t_{\rm L}$	$V_{SD} \le 0.5 \text{ V}, E_I = 19.0 \ \mu\text{W/cm}^2$		100	200	μs
Rise time *Fig. 1,9	t _r	$V_{SD} \le 0.5 \text{ V}, C_L = 15 \text{ pF}$	_	10	_	ns
Fall time *Fig. 1, 9	t_{f}	$V_{SD} \le 0.5 \text{ V}, C_L = 15 \text{ pF}$	_	10	_	ns

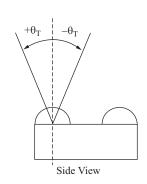
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■ Electrical-Optical Characteristics (continued)

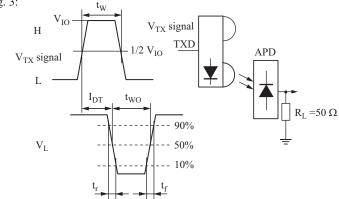
Note) Measurement circuit



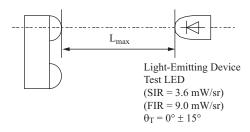
*Fig. 2:



*Fig. 3:

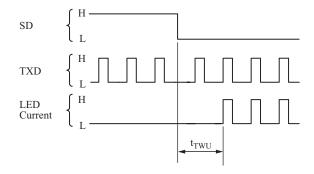


*Fig. 4:

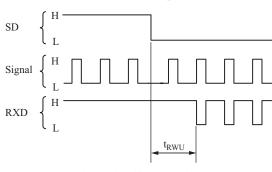


*Fig. 5:

TX Wake up time



*Fig. 6:

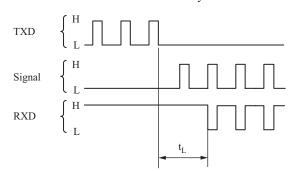


RX Wake up time

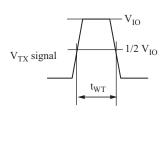
RXD state is uncertainty while receiver wakeup time. (RXD dose assert for an instant after SD negate.)

*Fig. 7:

Receiver latency time



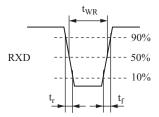
*Fig. 8:



■ Electrical-Optical Characteristics (continued)

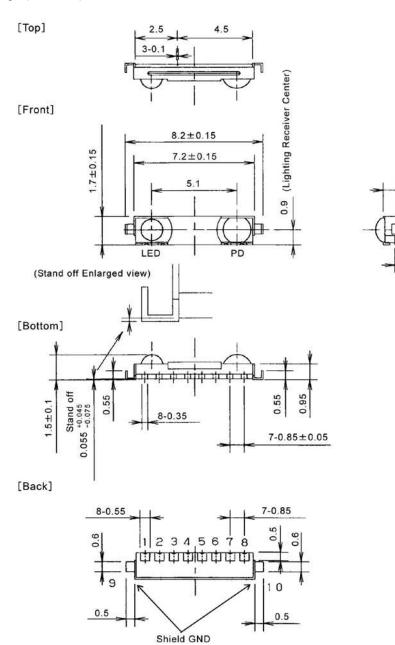
Note) Measurement circuit (continued)

*Fig. 9:



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■ Package (Unit: mm)



• Pin name

- $1. \ V_{LEDA} \qquad \qquad 6. \ \ V_{CC}$
- $2.\ V_{IO} \qquad \qquad 7.\ \ N.C.$
- 3. TXD 8. GND
- 4. RXD 9. Shield GND
- 5. SD 10. Shield GND

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